

Product Change Notification - KSRA-14MRKE725

Date: 18 Jul 2017
Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; 8-bit PIC Microcontrollers
Notification subject: CCB 3028 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.25um TSMC wafer technology available in 44L QFN package at NSEB assembly
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 44L QFN package at NSEB assembly site.

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB Assembly Site	NSEB Assembly Site
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	July 2017						-->	January 2018				
	26	27	28	29	30	31		01	02	03	04	05
Initial PCN Issue Date				X								
Qual Report Availability								X				
Final PCN Issue Date								X				

Method to Identify Change:

Traceability code

Qualification Plan:

Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:

July 18, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-14MRKE725_Affected CPN.pdf](#)
- [PCN_KSRA-14MRKE725_Qual Plan.pdf](#)
- [PCN_KSRA-14MRKE725_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-14MRKE725
CATALOG_PART_NBR
DSPIC33FJ128GP204-E/ML
DSPIC33FJ128GP204-I/ML
DSPIC33FJ128GP204T-E/ML
DSPIC33FJ128GP204T-I/ML
DSPIC33FJ128GP804-E/ML
DSPIC33FJ128GP804-H/ML
DSPIC33FJ128GP804-I/ML
DSPIC33FJ128GP804T-E/ML
DSPIC33FJ128GP804T-H/ML
DSPIC33FJ128GP804T-I/ML
DSPIC33FJ128MC204-E/ML
DSPIC33FJ128MC204-I/ML
DSPIC33FJ128MC204T-E/ML
DSPIC33FJ128MC204T-I/ML
DSPIC33FJ128MC804-E/ML
DSPIC33FJ128MC804-H/ML
DSPIC33FJ128MC804-I/ML
DSPIC33FJ128MC804T-E/ML
DSPIC33FJ128MC804T-H/ML
DSPIC33FJ128MC804T-I/ML
DSPIC33FJ16GP304-I/ML
DSPIC33FJ16GP304T-E/ML
DSPIC33FJ16GP304T-I/ML
DSPIC33FJ16GS404-50I/ML
DSPIC33FJ16GS404-E/ML
DSPIC33FJ16GS404-H/ML
DSPIC33FJ16GS404-I/ML
DSPIC33FJ16GS404T-50I/ML
DSPIC33FJ16GS404T-E/ML
DSPIC33FJ16GS404T-H/ML
DSPIC33FJ16GS404T-I/ML
DSPIC33FJ16GS504-50I/ML
DSPIC33FJ16GS504-E/ML
DSPIC33FJ16GS504-H/ML
DSPIC33FJ16GS504-I/ML
DSPIC33FJ16GS504T-50I/ML
DSPIC33FJ16GS504T-E/ML
DSPIC33FJ16GS504T-H/ML
DSPIC33FJ16GS504T-I/ML
DSPIC33FJ16MC304-E/ML
DSPIC33FJ16MC304-H/ML
DSPIC33FJ16MC304-I/ML
DSPIC33FJ16MC304T-E/ML

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DSPIC33FJ32GP204-I/ML
DSPIC33FJ32GP204T-E/ML
DSPIC33FJ32GP204T-I/ML
DSPIC33FJ32GP304-E/ML
DSPIC33FJ32GP304-I/ML
DSPIC33FJ32GP304T-E/ML
DSPIC33FJ32GP304T-I/ML
DSPIC33FJ32MC204-E/ML
DSPIC33FJ32MC204-H/ML
DSPIC33FJ32MC204-I/ML
DSPIC33FJ32MC204T-E/ML
DSPIC33FJ32MC204T-I/ML
DSPIC33FJ32MC204T-V/MLC21
DSPIC33FJ32MC204-V/MLC21
DSPIC33FJ32MC304-E/ML
DSPIC33FJ32MC304-I/ML
DSPIC33FJ32MC304T-E/ML
DSPIC33FJ32MC304T-I/ML
DSPIC33FJ64GP204-E/ML
DSPIC33FJ64GP204-I/ML
DSPIC33FJ64GP204T-E/ML
DSPIC33FJ64GP204T-I/ML
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DSPIC33FJ64GP804T-I/ML
DSPIC33FJ64MC204-E/ML
DSPIC33FJ64MC204-E/ML042
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DSPIC33FJ64MC204T-E/ML042
DSPIC33FJ64MC204T-I/ML
DSPIC33FJ64MC804-E/ML
DSPIC33FJ64MC804-H/ML
DSPIC33FJ64MC804-I/ML
DSPIC33FJ64MC804T-E/ML
DSPIC33FJ64MC804T-H/ML
DSPIC33FJ64MC804T-I/ML
HA7617-I/ML035
HA7617-I/ML040
HA7617T-I/ML035
HA7617T-I/ML040

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CATALOG_PART_NBR
HA7617T-I/ML044
PIC18F44J10-I/ML
PIC18F44J11-I/ML
PIC18F44J11T-I/ML
PIC18F44J50-I/ML
PIC18F44J50T-I/ML
PIC18F45J10-I/ML
PIC18F45J10T-I/ML
PIC18F45J11-I/ML
PIC18F45J11T-I/ML
PIC18F45J50-I/ML
PIC18F45J50T-I/ML
PIC18F46J11-I/ML
PIC18F46J11T-I/ML
PIC18F46J13-I/ML
PIC18F46J13T-I/ML
PIC18F46J50-I/ML
PIC18F46J50T-I/ML
PIC18F46J53-I/ML
PIC18F46J53T-I/ML
PIC18F47J13-I/ML
PIC18F47J13T-I/ML
PIC18F47J53-I/ML
PIC18F47J53T-I/ML
PIC18LF44J10-I/ML
PIC18LF44J11-I/ML
PIC18LF44J11T-I/ML
PIC18LF44J50-I/ML
PIC18LF44J50T-I/ML
PIC18LF45J10-I/ML
PIC18LF45J11-I/ML
PIC18LF45J11T-I/ML
PIC18LF45J50-I/ML
PIC18LF45J50T-I/ML
PIC18LF46J11-I/ML
PIC18LF46J11T-I/ML
PIC18LF46J13-I/ML
PIC18LF46J13T-I/ML
PIC18LF46J50-I/ML
PIC18LF46J50T-I/ML
PIC18LF46J53-I/ML
PIC18LF46J53T-I/ML
PIC18LF47J13-I/ML

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CATALOG_PART_NBR
PIC18LF47J13T-I/ML
PIC18LF47J53-I/ML
PIC18LF47J53T-I/ML
PIC24FJ16GA004-E/ML
PIC24FJ16GA004-I/ML
PIC24FJ16GA004T-I/ML
PIC24FJ16GA004T-I/MLB5
PIC24FJ16GA004T-I/MLC09
PIC24FJ32GA004-E/ML
PIC24FJ32GA004-I/ML
PIC24FJ32GA004-I/MLB5
PIC24FJ32GA004T-E/ML
PIC24FJ32GA004T-I/ML
PIC24FJ32GA004T-I/MLB5
PIC24FJ32GA004T-I/MLC12
PIC24FJ32GA104-E/ML
PIC24FJ32GA104-I/ML
PIC24FJ32GA104-I/ML021
PIC24FJ32GA104-I/ML023
PIC24FJ32GA104-I/ML025
PIC24FJ32GA104T-E/ML
PIC24FJ32GA104T-I/ML
PIC24FJ32GA104T-I/ML021
PIC24FJ32GA104T-I/ML023
PIC24FJ32GA104T-I/ML024
PIC24FJ32GA104T-I/ML025
PIC24FJ32GB004-I/ML
PIC24FJ32GB004T-I/ML
PIC24FJ48GA004-E/ML
PIC24FJ48GA004-I/ML
PIC24FJ48GA004T-I/ML
PIC24FJ48GA004T-I/ML022
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PIC24FJ64GA004-I/ML
PIC24FJ64GA004-I/MLB4
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PIC24FJ64GA104T-I/ML
PIC24FJ64GB004-I/ML
PIC24FJ64GB004T-I/ML
PIC24HJ128GP204-E/ML

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PIC24HJ128GP504-E/ML
PIC24HJ128GP504-H/ML
PIC24HJ128GP504-I/ML
PIC24HJ128GP504T-E/ML
PIC24HJ128GP504T-H/ML
PIC24HJ128GP504T-I/ML
PIC24HJ16GP304-H/ML
PIC24HJ16GP304-I/ML
PIC24HJ16GP304T-E/ML
PIC24HJ16GP304T-I/ML
PIC24HJ32GP204-E/ML
PIC24HJ32GP204-I/ML
PIC24HJ32GP204T-E/ML
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PIC24HJ32GP304-E/ML
PIC24HJ32GP304-I/ML
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